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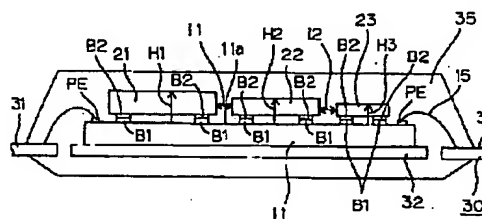
(54) **SEMICONDUCTOR DEVICE AND ASSEMBLY METHOD THEREOF**

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(57) Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor device, together with its assembling method, wherein a plurality of semiconductor chips are well jointed on the surface of a solid device (semiconductor chip, wiring board and the like).

SOLUTION: A plurality of child chips 21, 22 and 23 are jointed to an active surface 11a of a parent chip 1 and constitute a multi-chip type semiconductor device of chip-on-chip structure. The child chips 21, 22 and 23 have different heights H1, H2 and H3, respectively. Child chips 21, 22 and 23 are jointed to the active surface 11a in the order starting with shortest one. Thus, even if the child chips 21, 22 and 23 are arranged close to each other, no sucking collet for sucking a child chip at assembly interfere with a child chip already jointed to the active surface 11a.



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